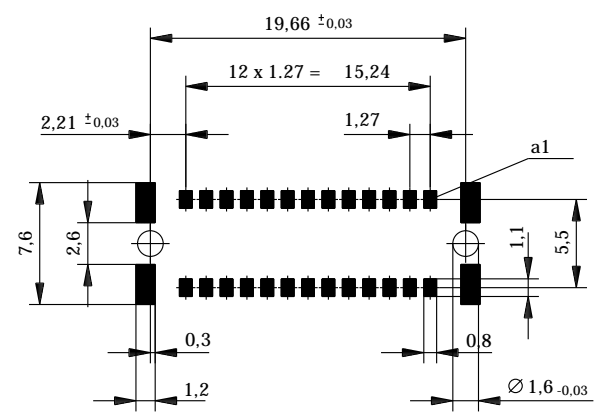
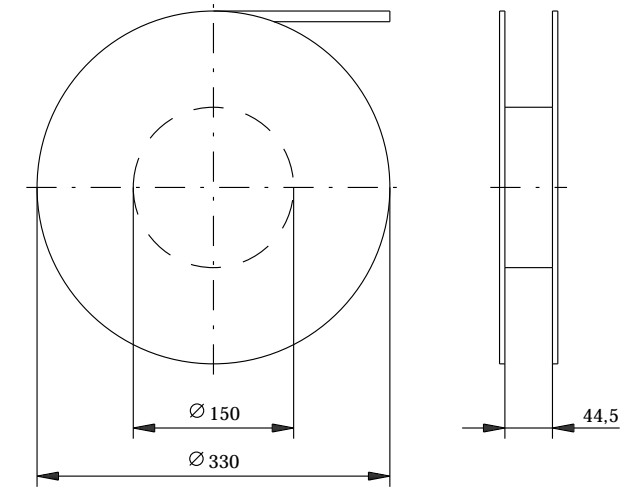


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

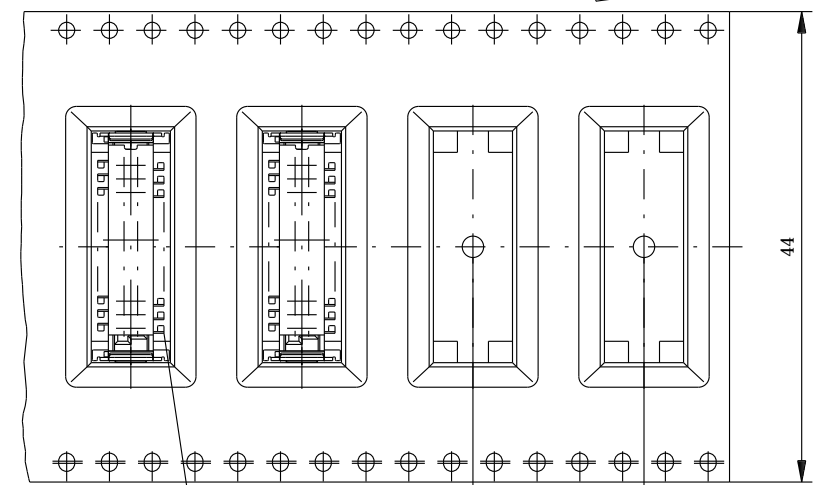


Anforderungsstufe 1
Performance Level 1
Kontaktbereich vergoldet
Mating Area gold plating
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating
Koplanarität der Anschlüsse ≤ 0.1mm
Coplanarity Area of Termination ≤ 0.1 mm

Verpackt in Gurtverpackung - Tape on Reel Packaging
Verpackungseinheit: 280 Stück - Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



BA7-13 - 8 mm Bauhöhe
type 7-13 - Low Profile

Information:		Tolerances	Scale 3:1
All rights reserved. Only for information. To insure that this is the latest version of this drawing, please contact one of the ERNI companies before using.		All Dimensions in mm	Angaben zu entsprechender Ident-Nr. siehe Fertigungsunterlagen For further information about I.D. number see manufacturing document.
Subject to modification without prior notice. Drawing will not be updated.		Designation Federl. SMC-B 26-SMD-BA7-13 Female SMC-B 26-SMD-type7-13	
www.ERNI.com		154806	
b	17.11.2005	SMC	
Index	Date	V:0059777.SZA	

Consider protection memo from DIN 34